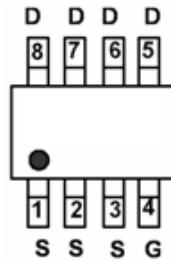


## 40V(D-S) N-Channel Enhancement Mode Power MOS FET

**General Features**

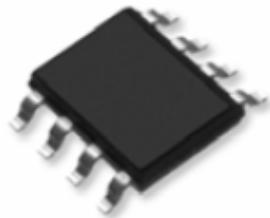
- $V_{DS} = 40V, I_D = 9A$
- $R_{DS(ON)} < 16m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} < 24m\Omega @ V_{GS}=4.5V$
- High density cell design for ultra low  $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

**Lead Free**

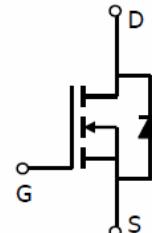
Marking and pin assignment

**Application**

- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply

**PIN Configuration**

SOP-8 top view



Schematic diagram

**Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MSN0409W	MSN0409W	SOP-8	Ø330mm	12mm	2500 units

**Absolute Maximum Ratings ( $T_C=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	9	A
Drain Current-Continuous( $T_C=100^\circ C$ )	$I_D (100^\circ C)$	6.4	A
Pulsed Drain Current	$I_{DM}$	40	A
Maximum Power Dissipation	$P_D$	2	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

**Thermal Characteristic**

Thermal Resistance,Junction-to-Ambient <sup>(Note 2)</sup>	$R_{\theta JA}$	62.5	°C/W
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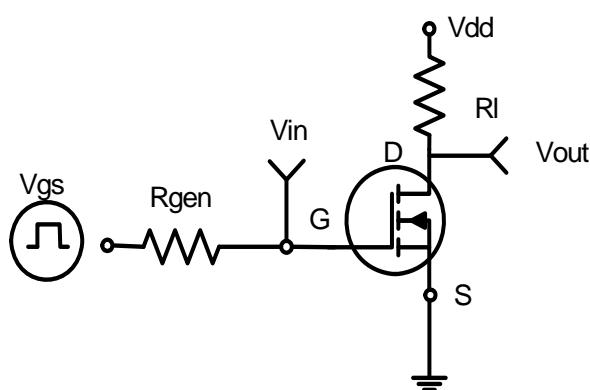
**Electrical Characteristics ( $T_A=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	40	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=40V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.5	2.0	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=8A$	-	12.9	16	$m\Omega$
		$V_{GS}=4.5V, I_D=4A$	-	18.9	24	$m\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=5V, I_D=8A$	33	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$C_{iss}$	$V_{DS}=20V, V_{GS}=0V, F=1.0MHz$	-	415	-	PF
Output Capacitance	$C_{oss}$		-	112	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	11	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=20V, R_L=2.5\Omega$ $V_{GS}=10V, R_{GEN}=3\Omega$	-	4	-	nS
Turn-on Rise Time	$t_r$		-	3	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	15	-	nS
Turn-Off Fall Time	$t_f$		-	2	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=20V, I_D=8A, V_{GS}=10V$	-	12	-	nC
Gate-Source Charge	$Q_{gs}$		-	3.2	-	nC
Gate-Drain Charge	$Q_{gd}$		-	3.1	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{SD}$	$V_{GS}=0V, I_S=9A$	-	0.8	1.2	V

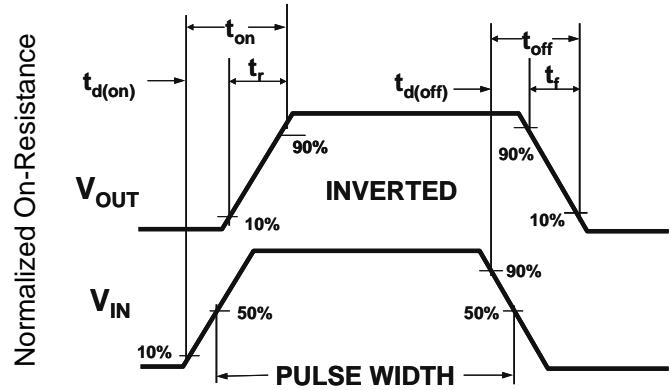
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

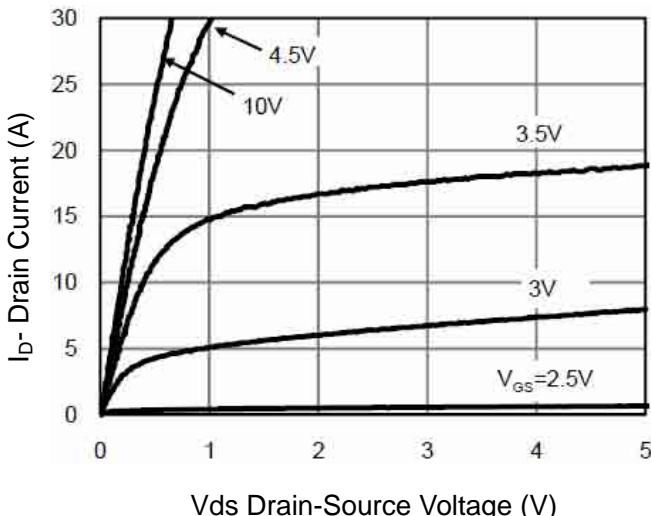
### Typical Electrical and Thermal Characteristics (Curves)



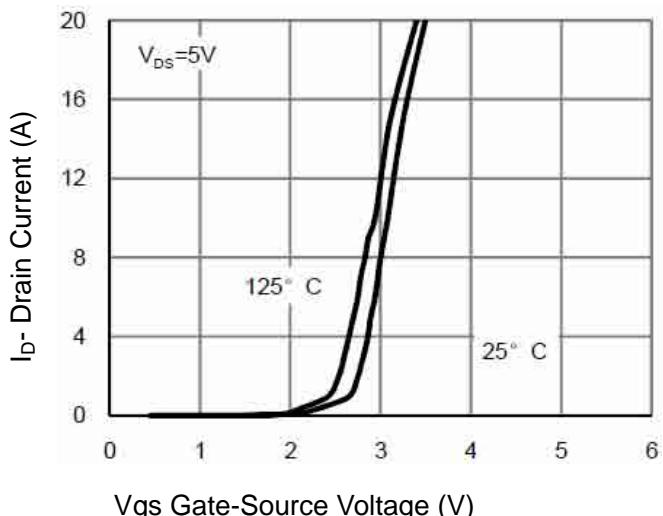
**Figure 1:Switching Test Circuit**



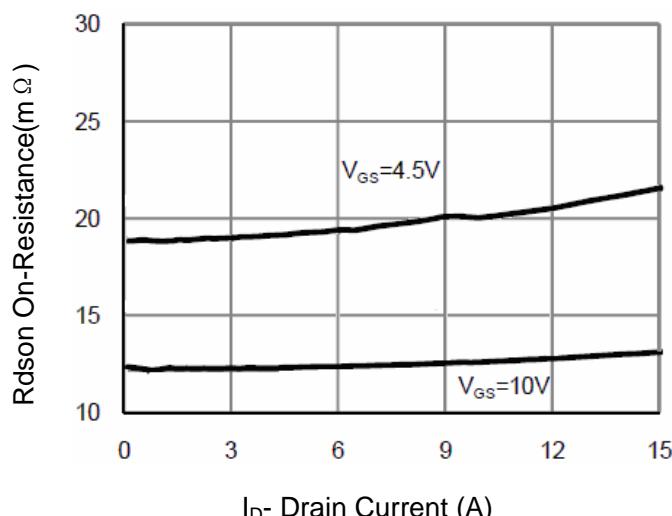
**Figure 2:Switching Waveforms**



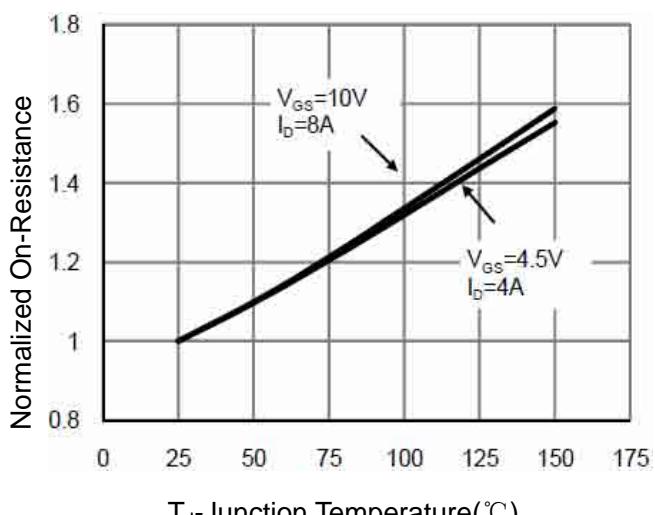
**Figure 3 Output Characteristics**



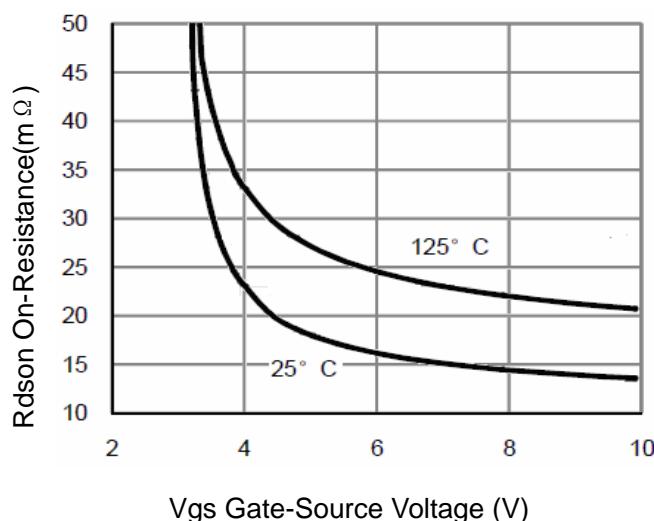
**Figure 4 Transfer Characteristics**



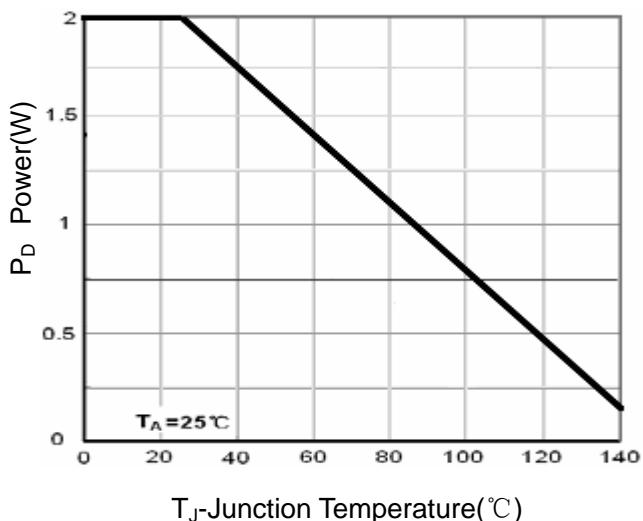
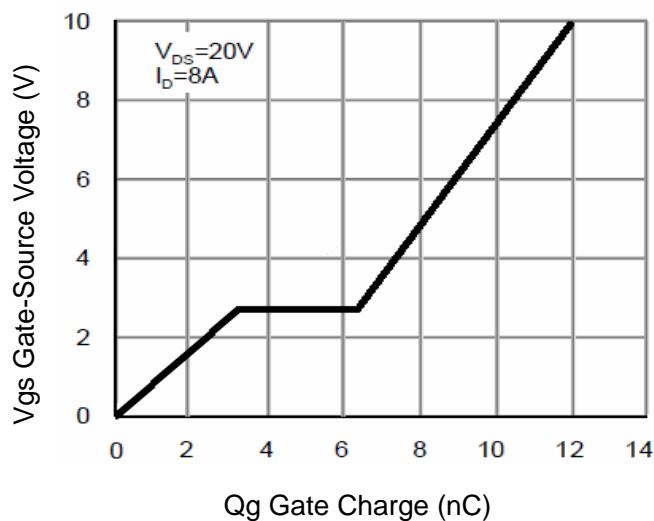
**Figure 5 Drain-Source On-Resistance**



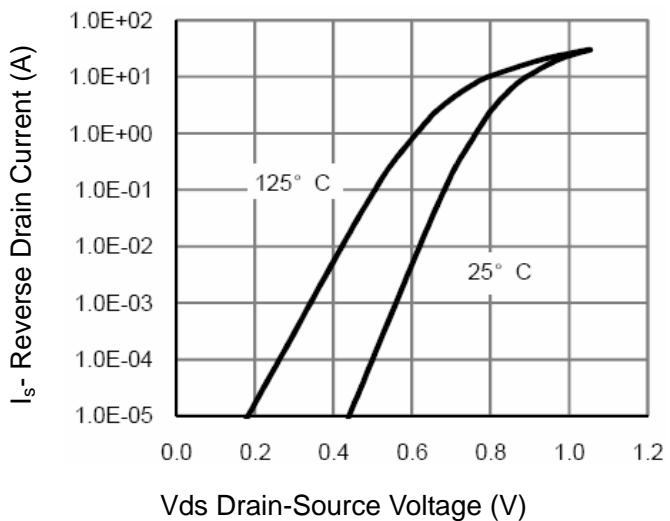
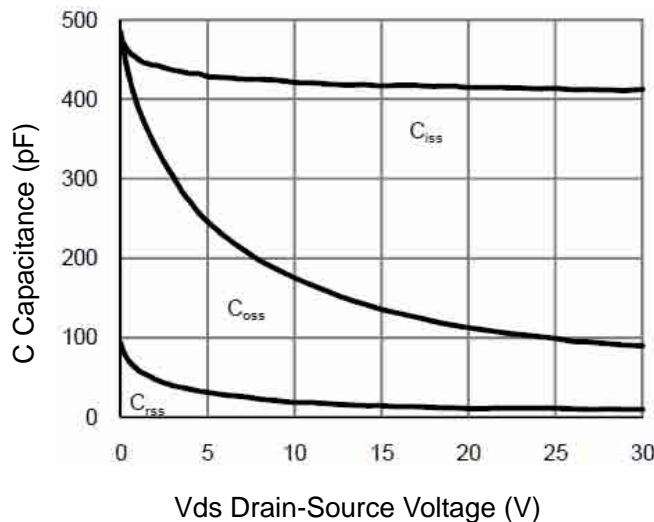
**Figure 6 Drain-Source On-Resistance**



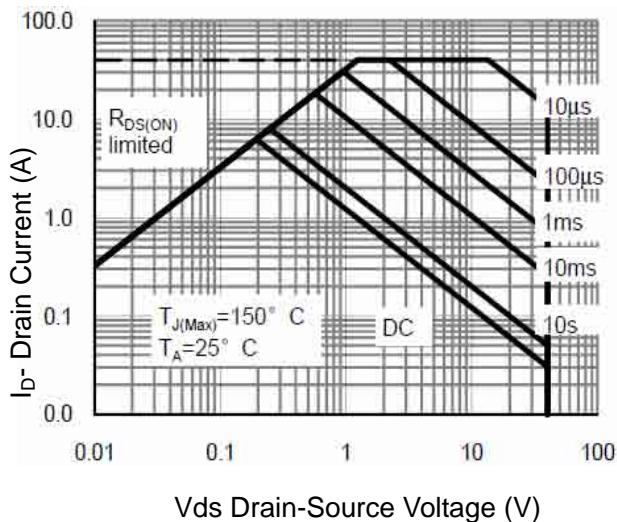
Vgs Gate-Source Voltage (V)

**Figure 7 Rdson vs Vgs**T<sub>J</sub>-Junction Temperature(°C)**Figure 8 Power Dissipation**

Qg Gate Charge (nC)

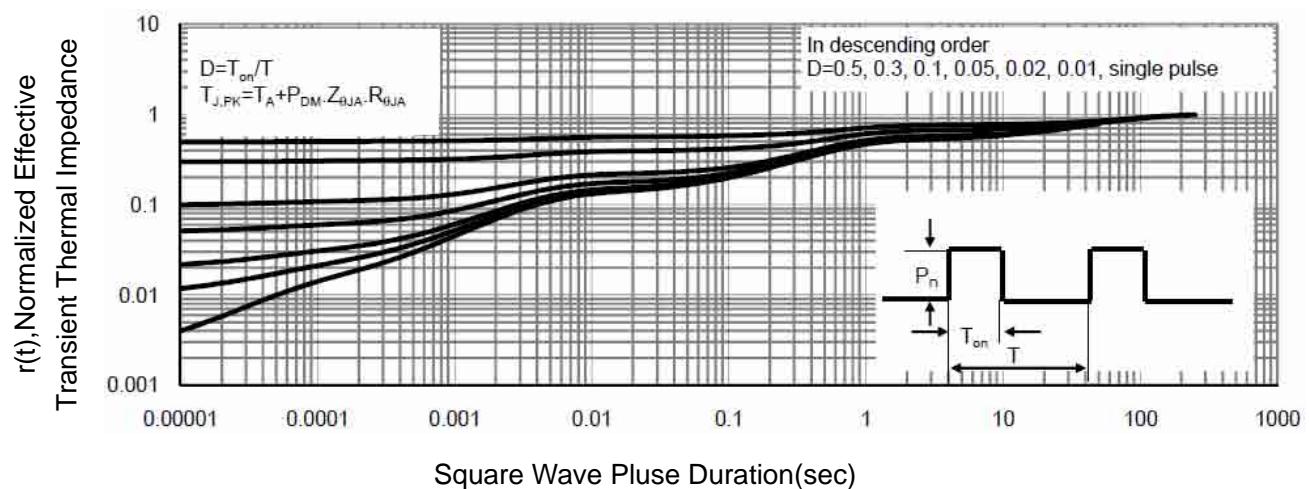
**Figure 9 Gate Charge**I<sub>s</sub>- Reverse Drain Current (A)**Figure 10 Source- Drain Diode Forward**

Vds Drain-Source Voltage (V)

**Figure 11 Capacitance vs Vds**

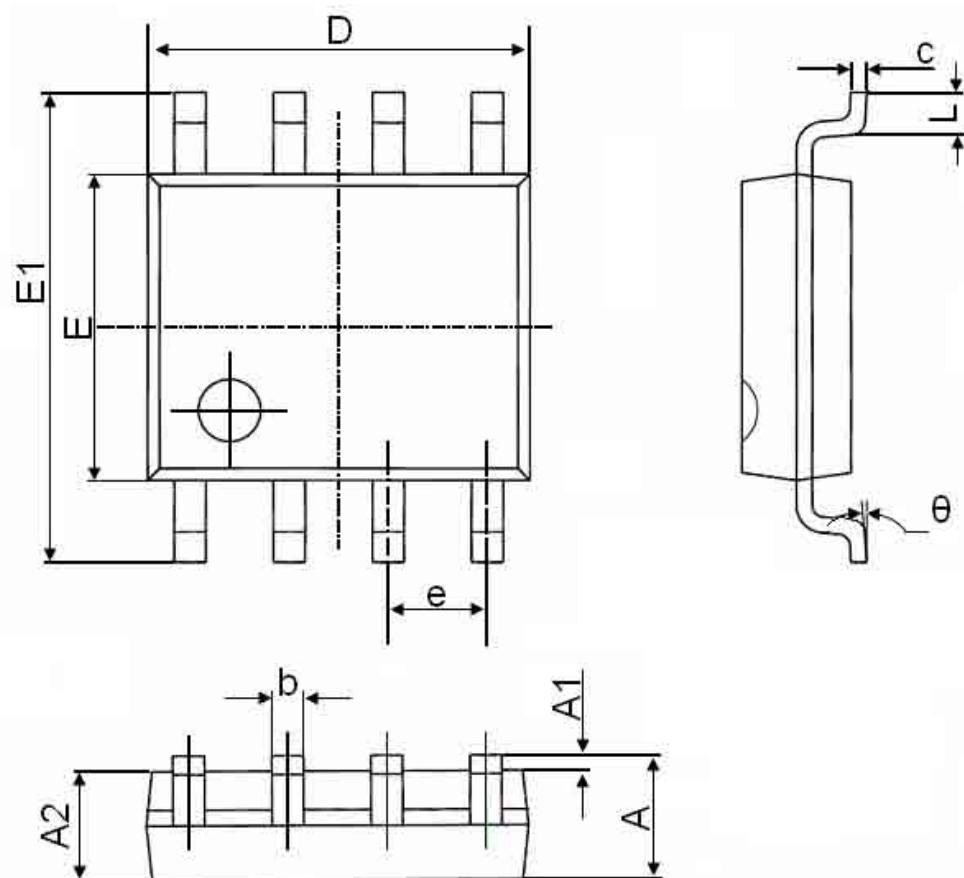
Vds Drain-Source Voltage (V)

**Figure 12 Safe Operation Area**



**Figure 13 Normalized Maximum Transient Thermal Impedance**

## SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°